

# ECE 471 – Embedded Systems

## Lecture 21

Vince Weaver

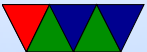
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# Announcements

- Don't forget Project status reports.
- HW#8 grades will be posted



# CANbus

- Automotive. Introduced by BOSCH, 1983
- One of OBD-II protocols
- differential, 2 wires, 1MBps important things like engine control
- single wire, slower cheaper, hvac, radio, airbags



# CANbus Protocol

- id, length code, up to 8 bytes of data id (usually 11 or 29 bits) type and who is sending it. Also priority (lower is higher) length is 4 bits. some always send 8 and pad with zeros
- Type is inferred from id. Can be things like engine RPM, etc
- DBC database has the ids and values. ASCII text database, hard to get legally.



- Dominant/Recessive. Message with lowest ID wins arbitration.
- CAN-FD – extended version with larger sizes



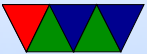
# CANbus Linux

- Can4linux – `open("/dev/can0"); read(); write();`  
External project?
- SocketCAN – contributed by Volkswagen. In kernel.  
Uses socket interface. `/Documentation/networking/can.txt`



# CANbus on Pi

- No



# ISA Bus

- Introduced with IBM-PC in 1981
- 8-bit (4.77MHz) then 16-bit (8MHz)
- +/-5V, +/-12V, 8 data, 20 address, DMA, IRQ
- Replaced by VLB (more pins, extra header), EISA (double pins in same connector), MCA micro-channel (different proprietary from IBM)





- Not enumerable at first, set jumpers. Later “Plug-n-Play”



# LPC Bus

- Low-pin-count bus
- Intel, 1998, try to get rid of ISA
- Things like PS/2, Serial ports, floppy, etc.  
Still used for TPM Trusted Computing nonsense
- Replace 16-bit 8.33MHz parallel bus with 4-bit wide 33.3MHz bus. Only 7 wires. Easier to route than 72



# “Conventional” PCI Bus

- Peripheral Component Interconnect
- Enumerable
- 1993, intel
- 62-pins, parallel, 133MB/s
- Extended with 32 or 64-bit versions, 33 or 66MHz, 3.3 or 5V. All slight differences in connectors to support all that.



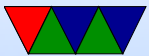
- AGP (Accelerated Graphics Card) for graphics cards. 1997. Direct connect to CPU (not shared), multiple channels, faster clock
- PCI-X 1998, extension to 133MHz. Not to be confused with PCI-Express (PCIe)



# PCI protocol

- 256B Config space, mapped into CPU address. Small area system can probe, used to setup larger mappings
- Can have on-board ROM that can be executed. Problem when using on non-x86 systems (emulators needed? special [expensive] PowerPC versions?)
- Latency timers keep bus-master from hogging bus
- 4 interrupt lines, can be shared. Level rather than edge-triggered interrupts make sharing easier



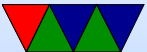


# PCIe

- PCI-express, 2003
- Serial, replaced point-to-point with lanes, packet-based  
x1, x2, x4, x8 x16, x32
- Compatible with PCI at software level
- Differential Signaling
- External – Thunderbolt



- Serial better due to timing skew
- New x86 audrino quark has PCIe





# PCleexpress Mini

- PCIe x1, USB, SMBus, etc
- Smaller card



# PCMCIA Bus

- Personal Computer Memory Control International Association
- 16-bit
- Cardbus, 32-bit
- Mostly replaced these days



# PC/104 Bus

- Stackable small x86 boards usually
- Run ISA or PCI signals up vertically



# VME Bus

- m68k bus but generic enough
- Still found in some embedded systems



# Other

- SATA, eSATA, PATA, SCSI (disk drives)
- Firewire
- RapidIO
- Quickpath QPI
- Hypertransport
- Thunderbolt (requested)



- List of competing busses at end of USB wiki article



# Measuring Power and Energy

- Sense resistor or Hall Effect sensor gives you the current
- Sense resistor is small resistor. Measure voltage drop. Current  $V=IR$  Ohm's Law, so  $V/R=I$
- Voltage drops are often small (why?) so you may need to amplify with instrumentation amplifier
- Then you need to measure with A/D converter
- $P = IV$  and you know the voltage



- How to get Energy from Power?





# Definitions

People often say Power when they mean Energy

- Dynamic Power – only consumed while computing
- Static Power – consumed all the time.  
Sets the lower limit of optimization

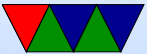


# Units

- Energy – Joules, kWh (3.6MJ), Therm (105.5MJ), 1 Ton TNT (4.2GJ), eV ( $1.6 \times 10^{-19}$  J), BTU (1055 J), horsepower-hour (2.68 MJ), calorie (4.184 J)
- Power – Energy/Time – Watts (1 J/s), Horsepower (746W), Ton of Refrigeration (12,000 Btu/h)
- Volt-Amps (for A/C) – same units as Watts, but not same thing
- Charge – mAh (batteries) – need voltage to convert to Energy

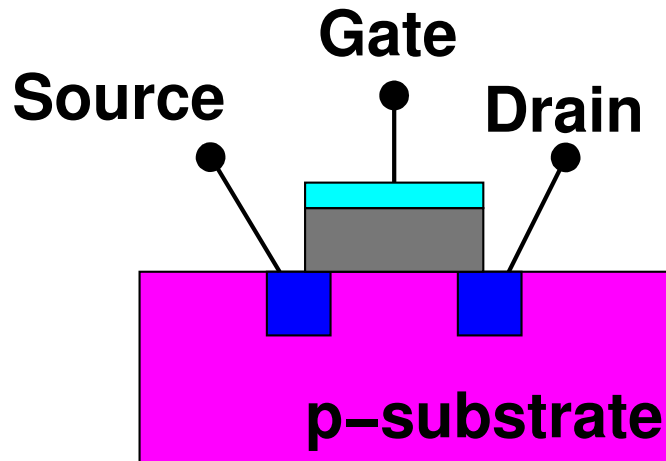


# CPU Power and Energy

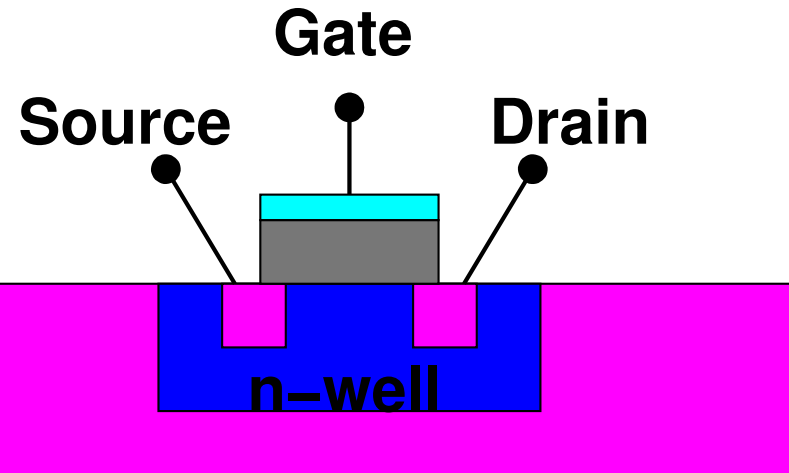


# CMOS Transistors

## N-MOSFET



## P-MOSFET



# CMOS Dynamic Power

- $P = C\Delta VV_{dd}\alpha f$

Charging and discharging capacitors big factor  
( $C\Delta VV_{dd}$ ) from  $V_{dd}$  to ground

$\alpha$  is activity factor, transitions per clock cycle

$f$  is frequency

- $\alpha$  often approximated as  $\frac{1}{2}$ ,  $\Delta VV_{dd}$  as  $V_{dd}^2$  leading to  
 $P \approx \frac{1}{2}CV_{dd}^2f$

- Some pass-through loss (V momentarily shorted)



# CMOS Dynamic Power Reduction

How can you reduce Dynamic Power?

- Reduce  $C$  – scaling
- Reduce  $V_{dd}$  – eventually hit transistor limit
- Reduce  $\alpha$  (design level)
- Reduce  $f$  – makes processor slower



# CMOS Static Power

- Leakage Current – bigger issue as scaling smaller.  
Forecast at one point to be 20-50% of all chip power before mitigations were taken.
- Various kinds of leakage (Substrate, Gate, etc)
- Linear with Voltage:  $P_{static} = I_{leakage}V_{dd}$



# Leakage Mitigation

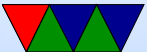
- SOI – Silicon on Insulator (AMD, IBM but not Intel)
- High-k dielectric – instead of SiO<sub>2</sub> use some other material for gate oxide (Hafnium)
- Transistor sizing – make only critical transistors fast; non-critical can be made slower and less leakage prone
- Body-biasing
- Sleep transistors





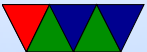
# Total Energy

- $E_{tot} = [P_{dynamic} + P_{static}]t$
- $E_{tot} = [(C_{tot}V_{dd}^2\alpha f) + (N_{tot}I_{leakage}V_{dd})]t$



# Delay

- $T_d = \frac{C_L V_{dd}}{\mu C_{ox} (\frac{W}{L}) (V_{dd} - V_t)}$
- Simplifies to  $f_{MAX} \sim \frac{(V_{dd} - V_t)^2}{V_{dd}}$
- If you lower f, you can lower  $V_{dd}$



# Thermal Issues

- Temperature and Heat Dissipation are closely related to Power
- If thermal issues, need heatsinks, fans, cooling



# Metrics to Optimize

- Power
- Energy
- MIPS/W, FLOPS/W (don't handle quadratic V well)
- *Energy \* Delay*
- *Energy \* Delay<sup>2</sup>*



# Power Optimization

- Does not take into account time. Lowering power does no good if it increases runtime.



# Energy Optimization

- Lowering energy can affect time too, as parts can run slower at lower voltages



# Energy Delay – Watt/t\*t

- Horowitz, Indermaur, Gonzalez (Low Power Electronics, 1994)
- Need to account for delay, so that lowering Energy does not made delay (time) worse
- Voltage Scaling – in general scaling low makes transistors slower
- Transistor Sizing – reduces Capacitance, also makes transistors slower



- Technology Scaling – reduces  $V$  and power.
- Transition Reduction – better logic design, have fewer transitions  
Get rid of clocks? Asynchronous? Clock-gating?

- Example with inverse ED (higher better):

Alpha 21064	SPEC=155	Power=30W	SPEC*SPEC/W=800
PPC603	SPEC=80	Power=3W	SPEC*SPEC/W=2100





# Energy Delay Squared– $E*t*t$

- Martin, Nyström, Péntzes – Power Aware Computing, 2002
- Independent of Voltage in CMOS
- $E*t$  can be misleading  
 $E_a=2E_b$ ,  $t_a=t_b/2$   
Reduce voltage by half,  $E_a=E_a/4$ ,  $t_a=2t_a$ ,  $E_a=E_b/2$ ,  
 $t_a=t_b$
- Can have arbitrary large number of delay terms in Energy



product, squared seems to be good enough

